

NOV 08 2002

TRADEMARK

FIG. 1

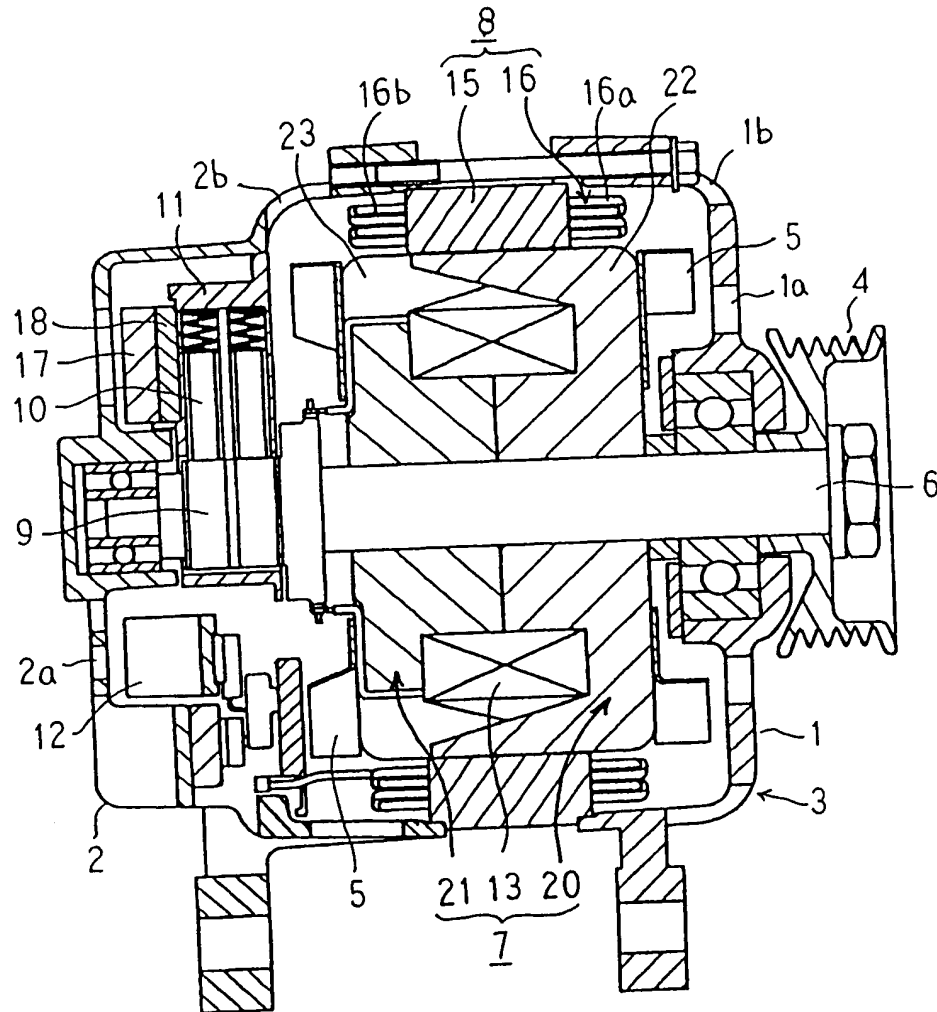


FIG. 2

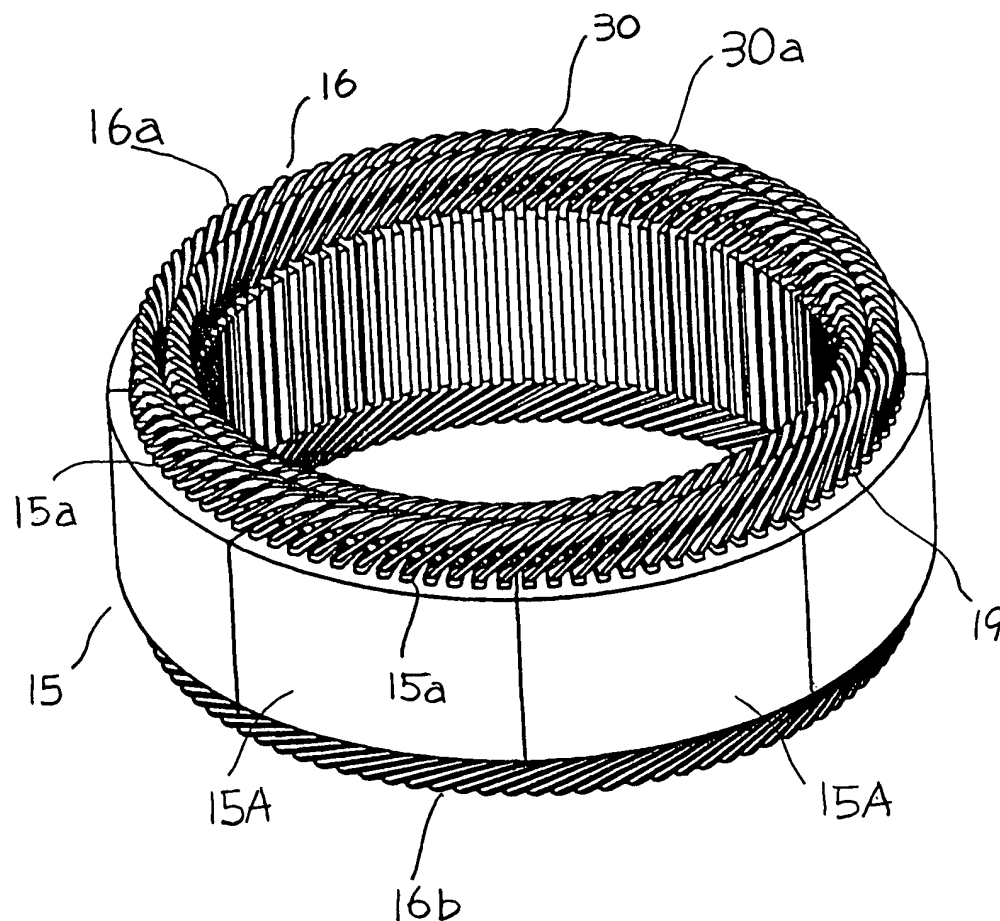


FIG. 3

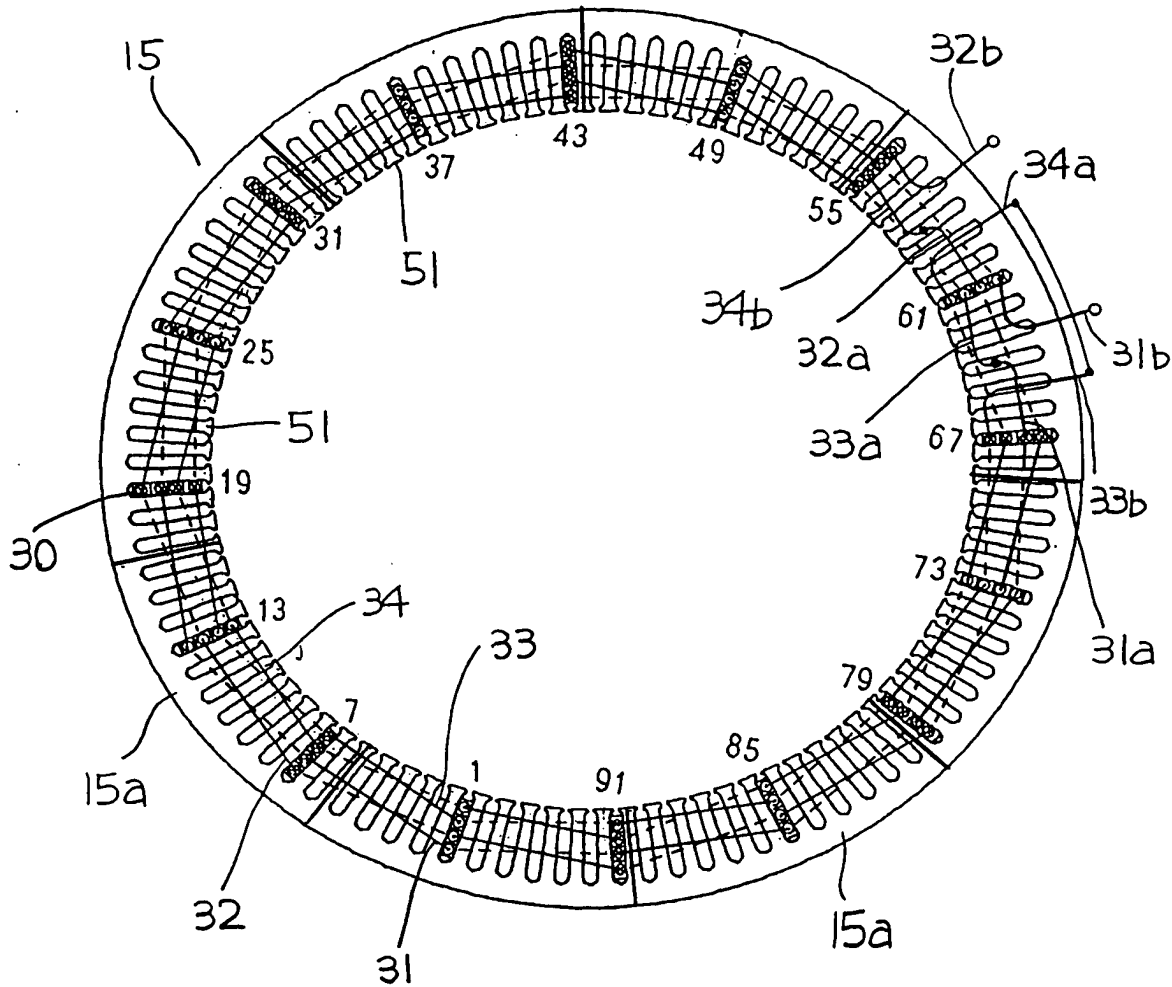


FIG. 4

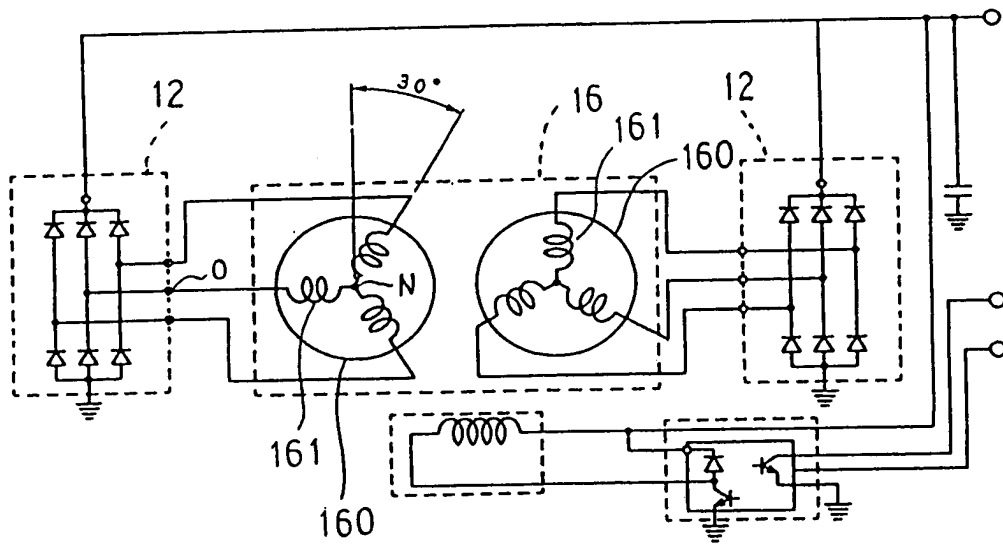


FIG. 5

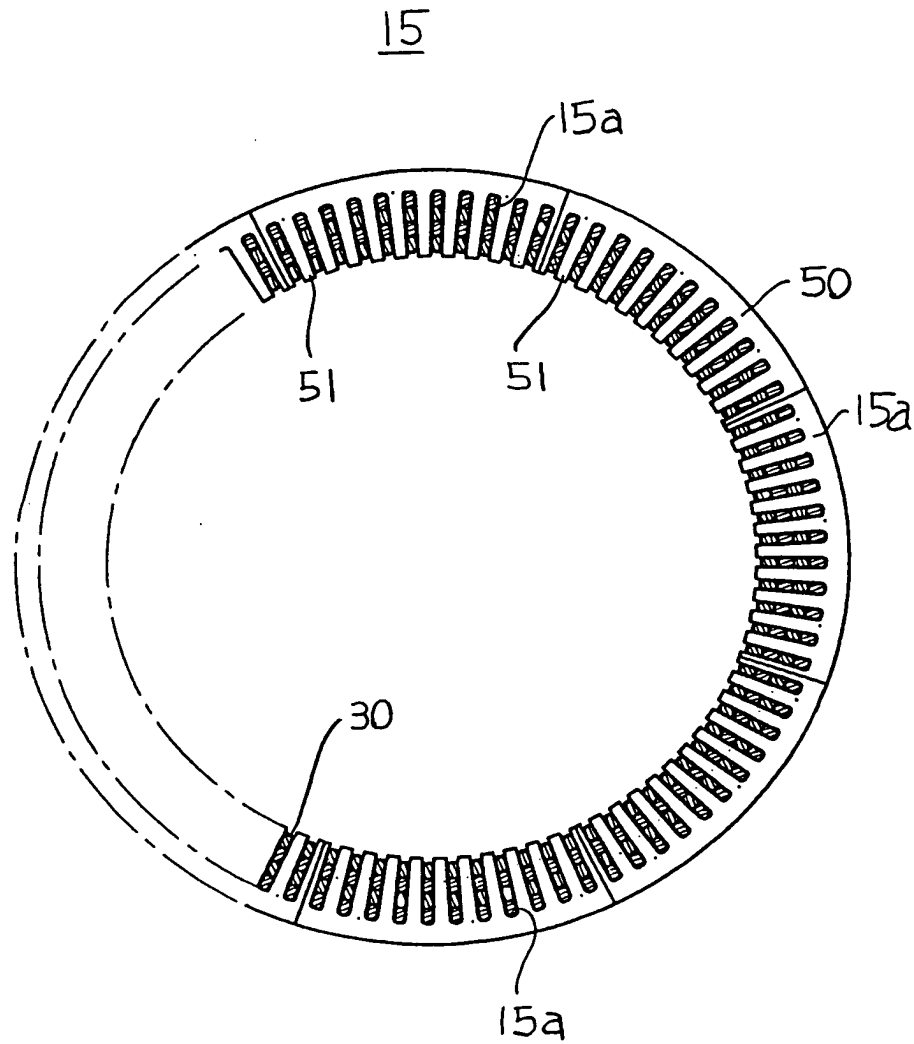


FIG. 6

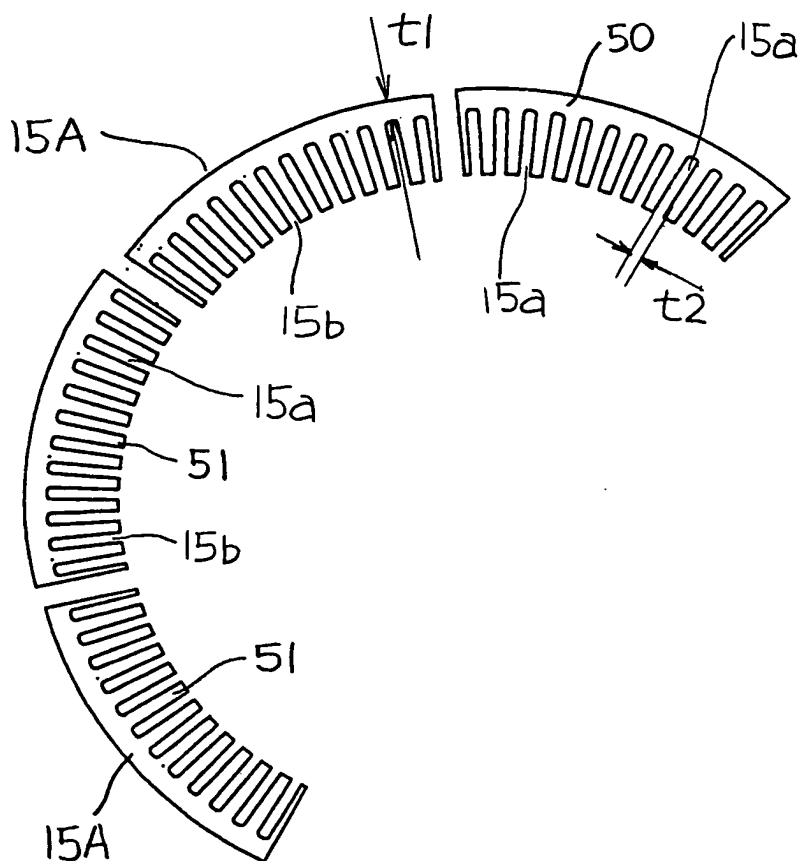




FIG. 7

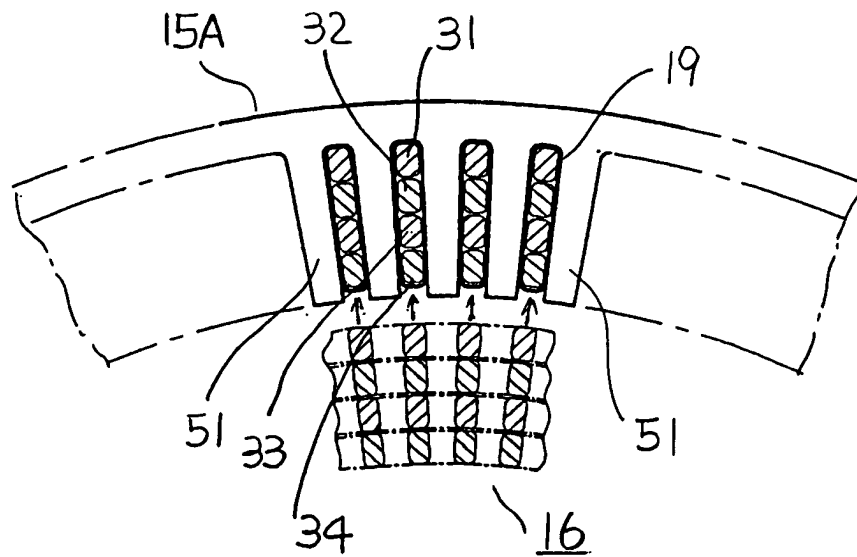


FIG. 8

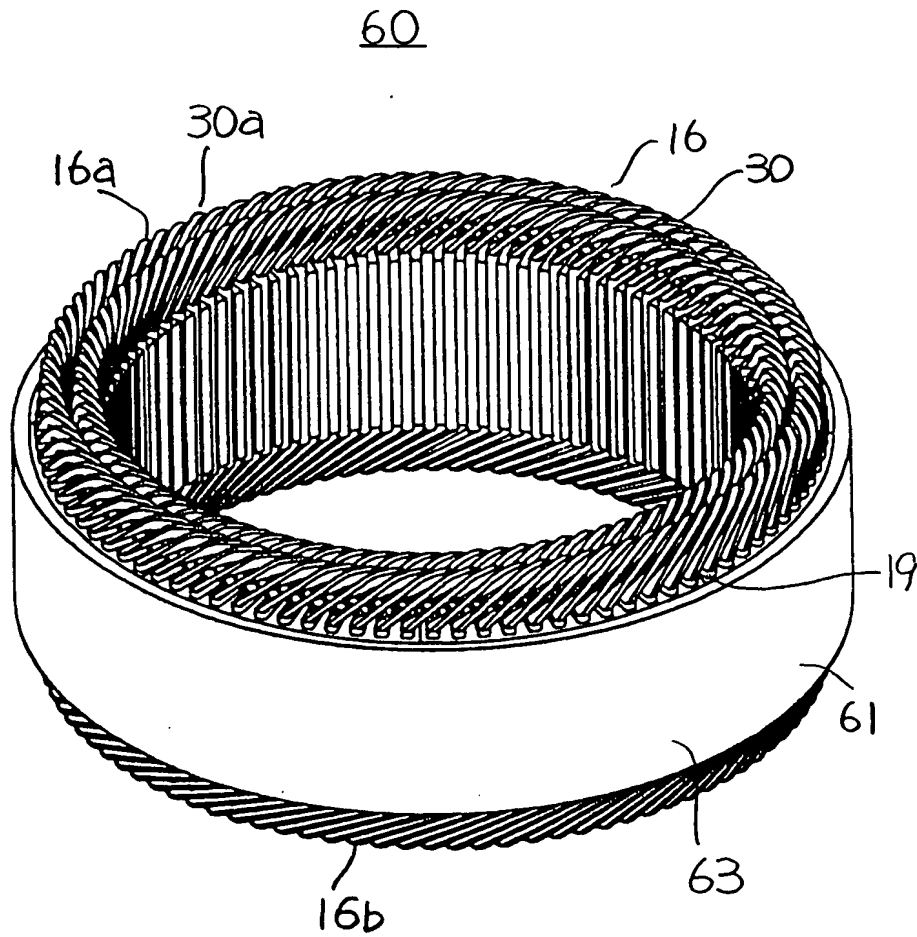


FIG. 9

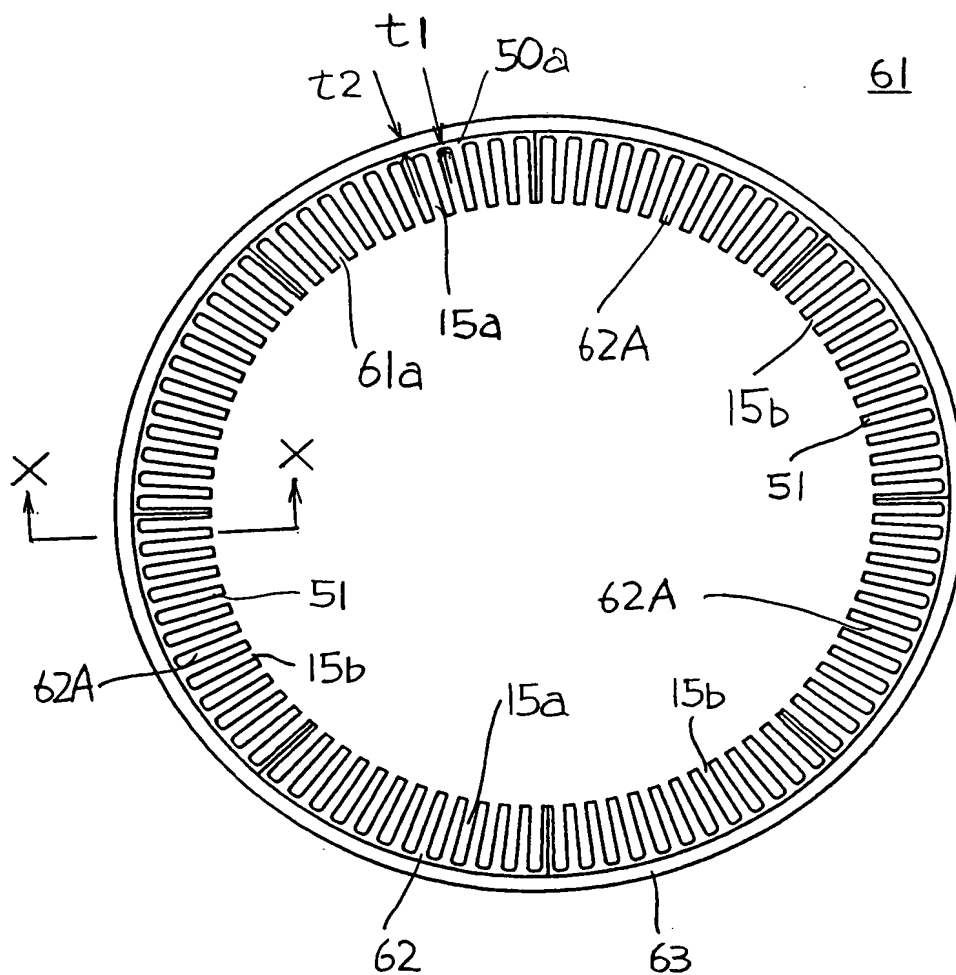
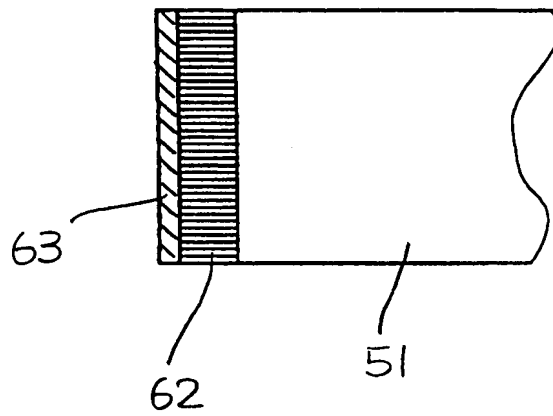


FIG. 10



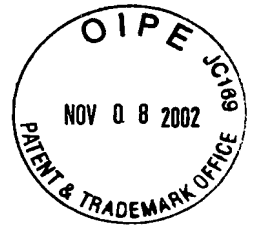


FIG. 11

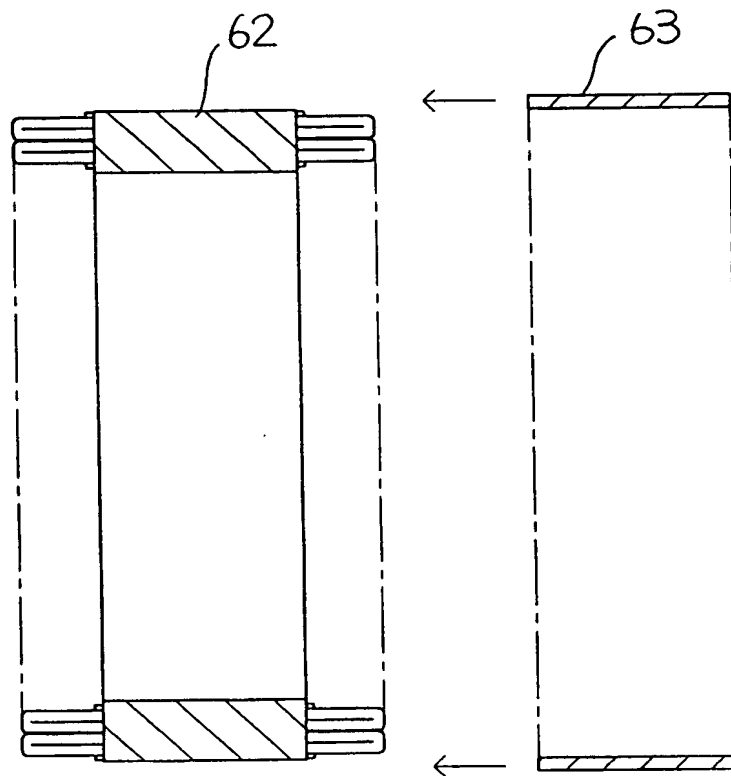


FIG. 12

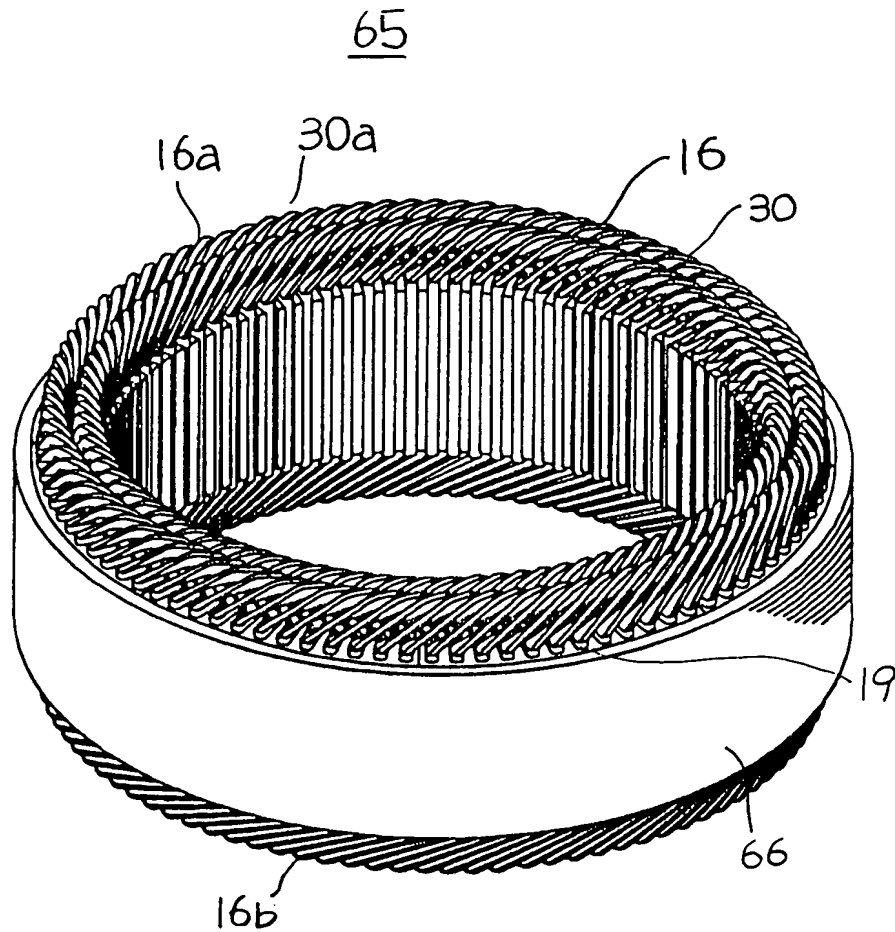




FIG. 13

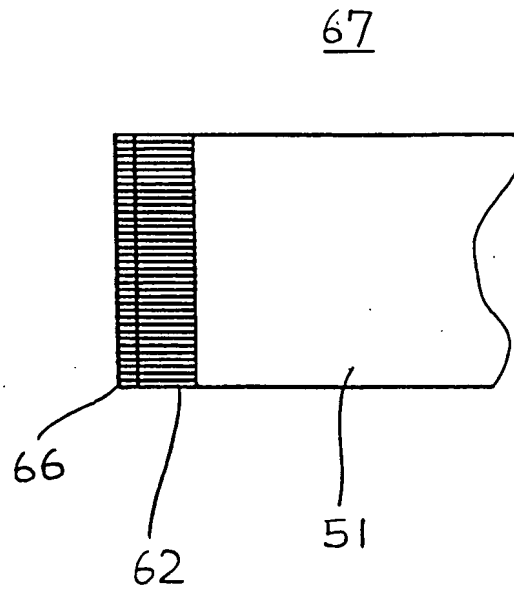


FIG. 14

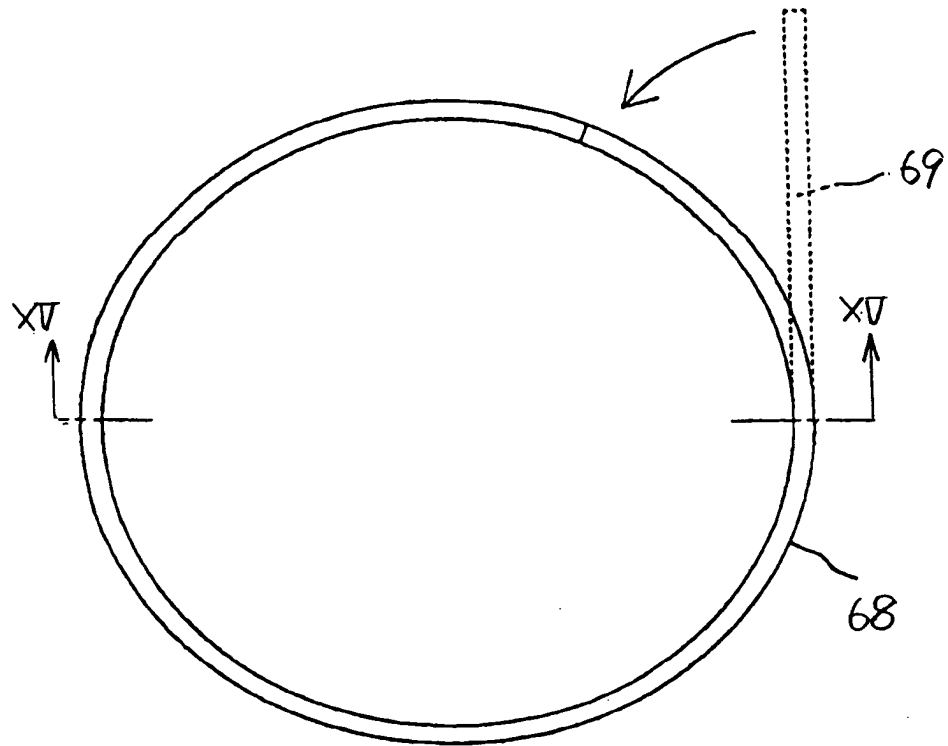


FIG. 15



FIG. 16

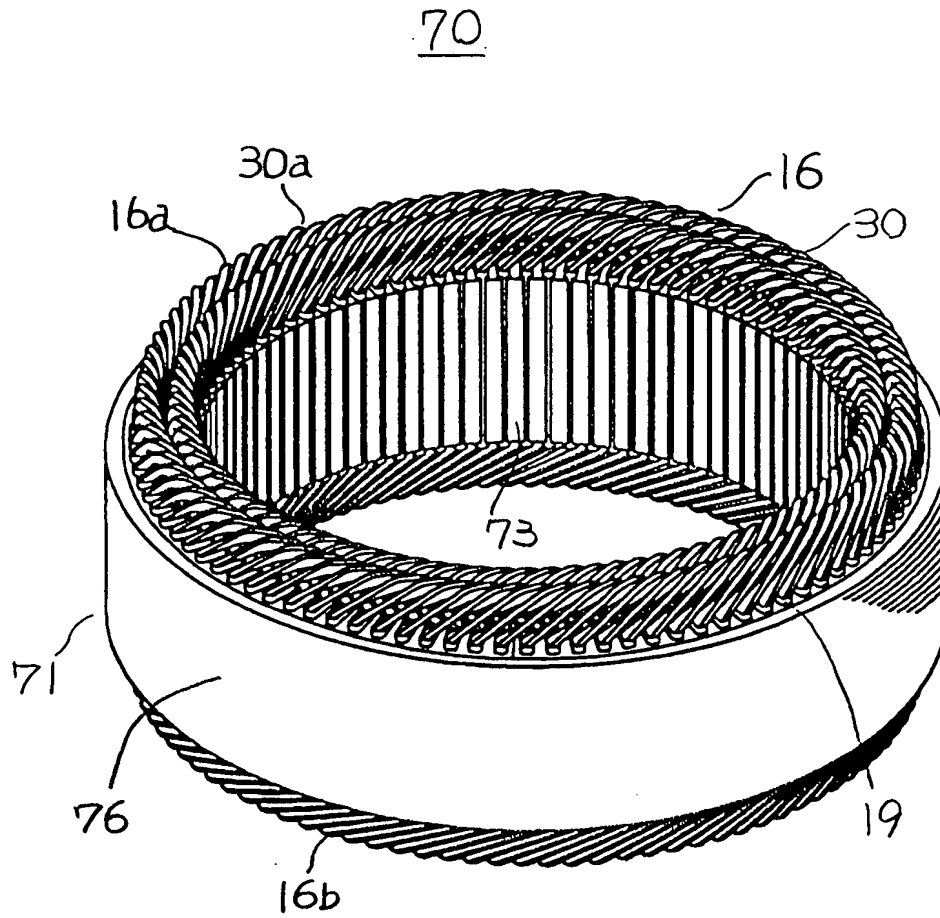


FIG. 17

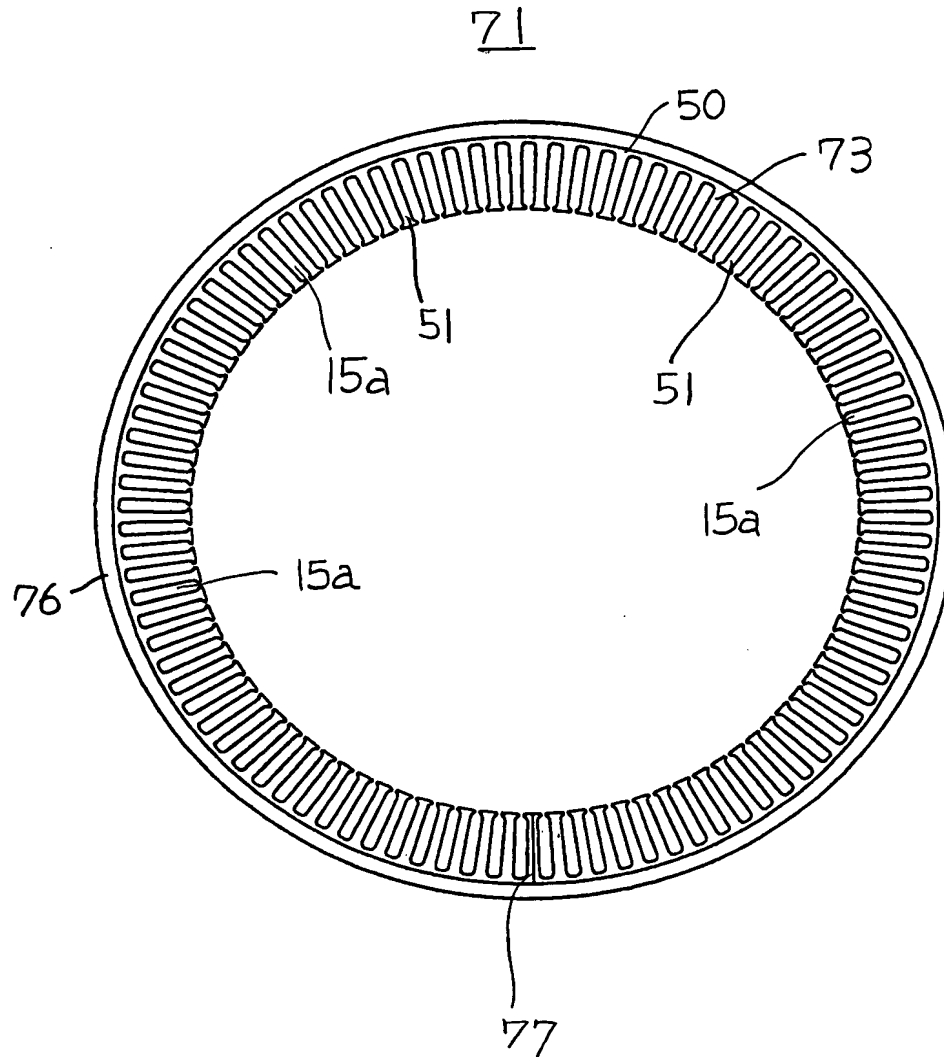


FIG. 18

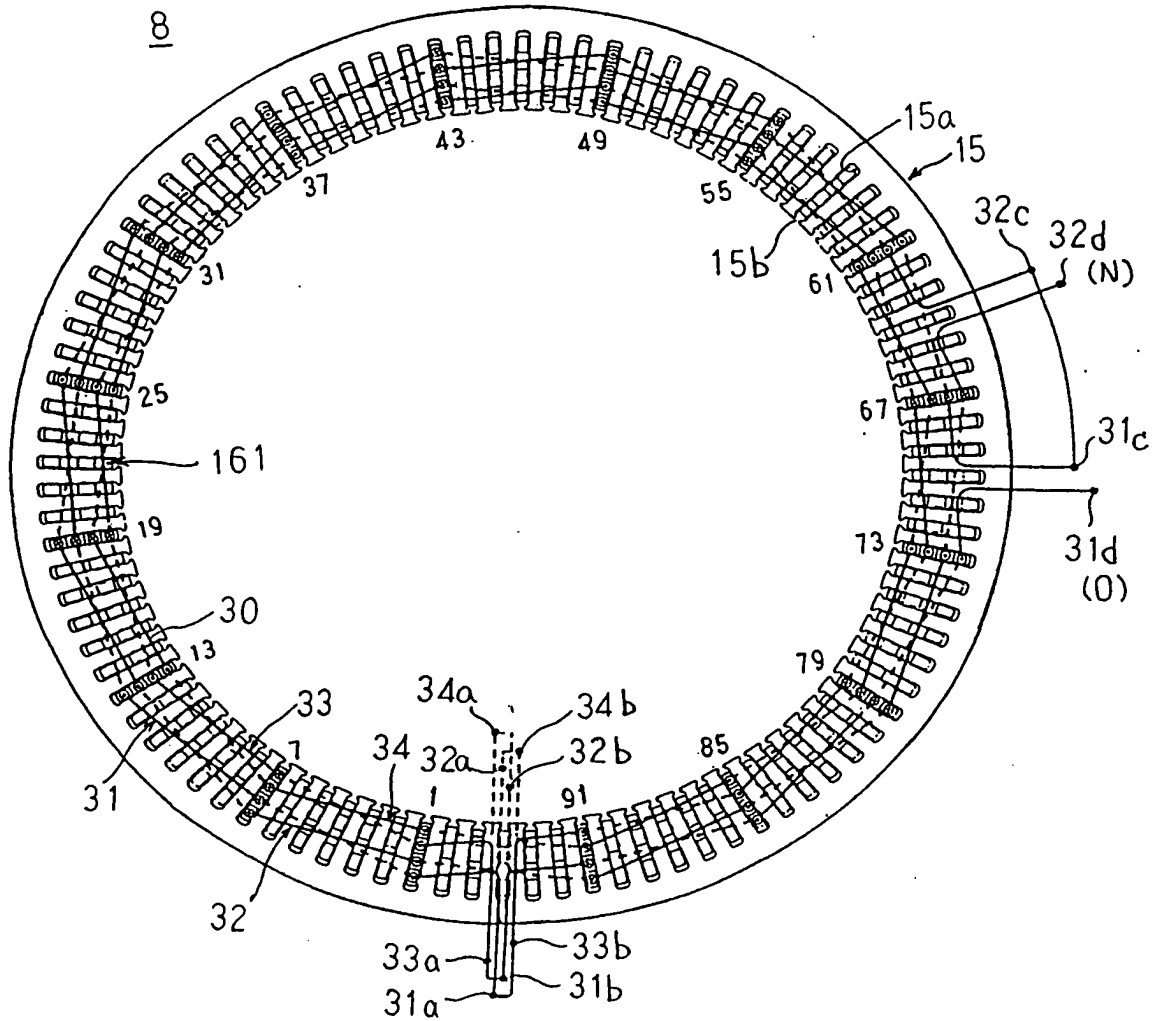




FIG. 19

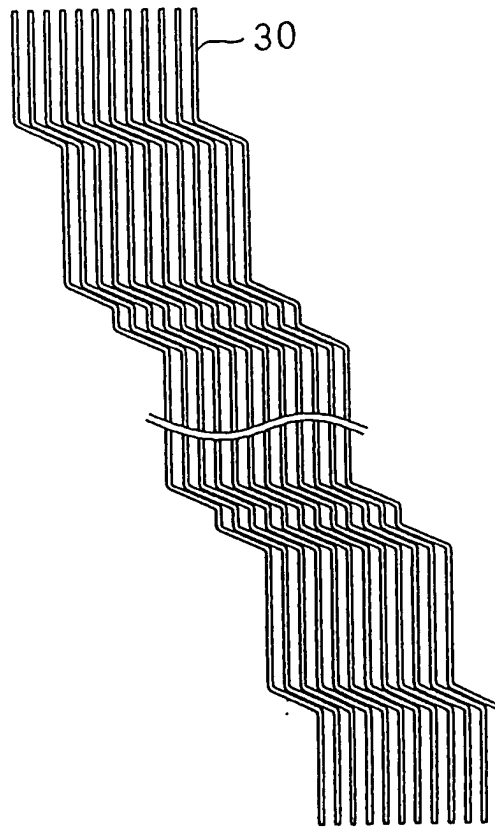


FIG. 20

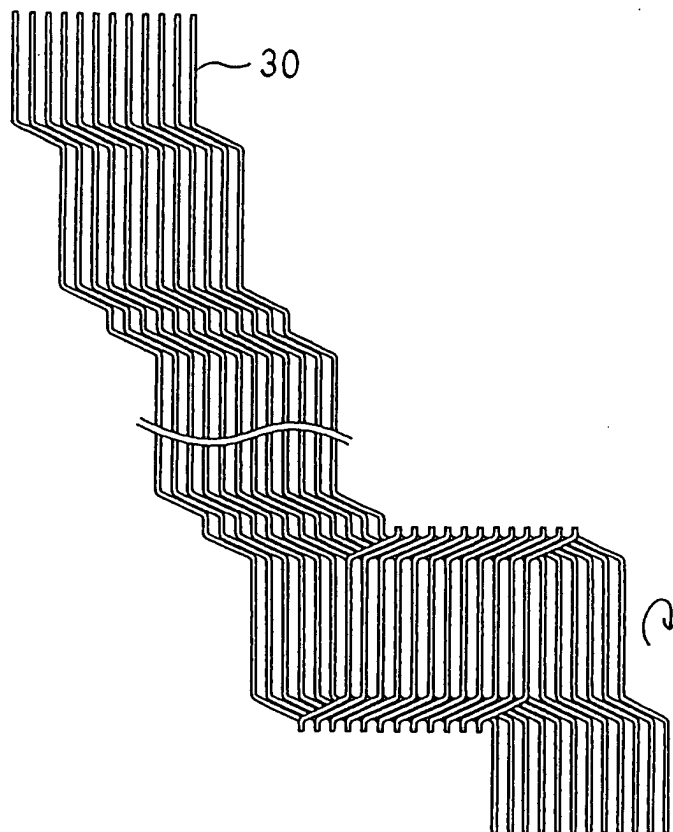




FIG. 21

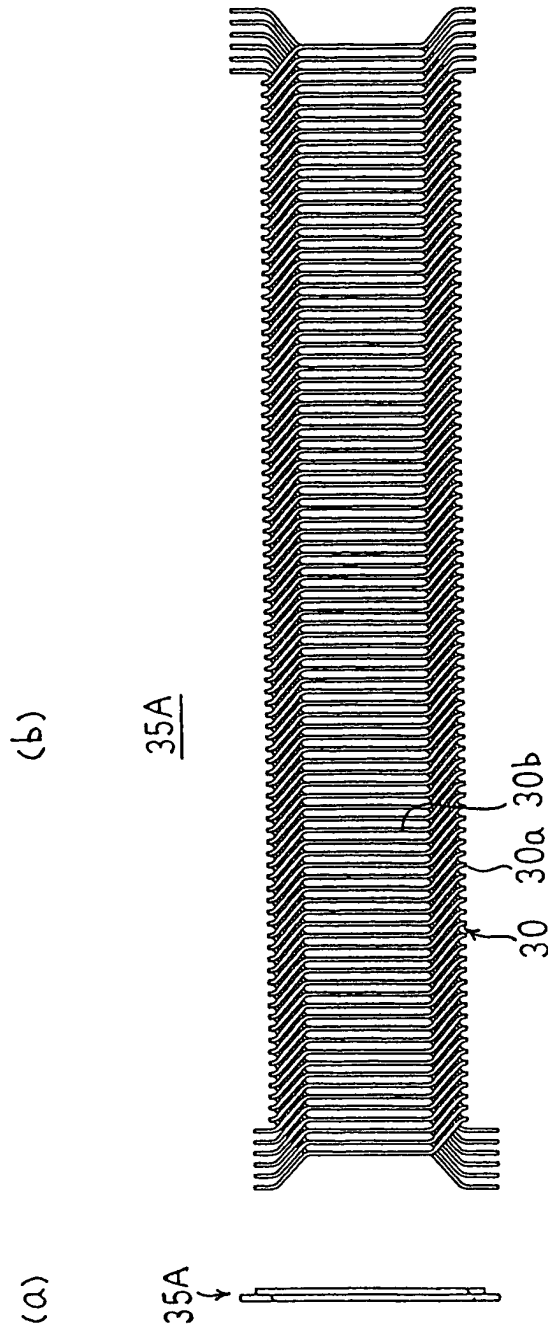


FIG. 22

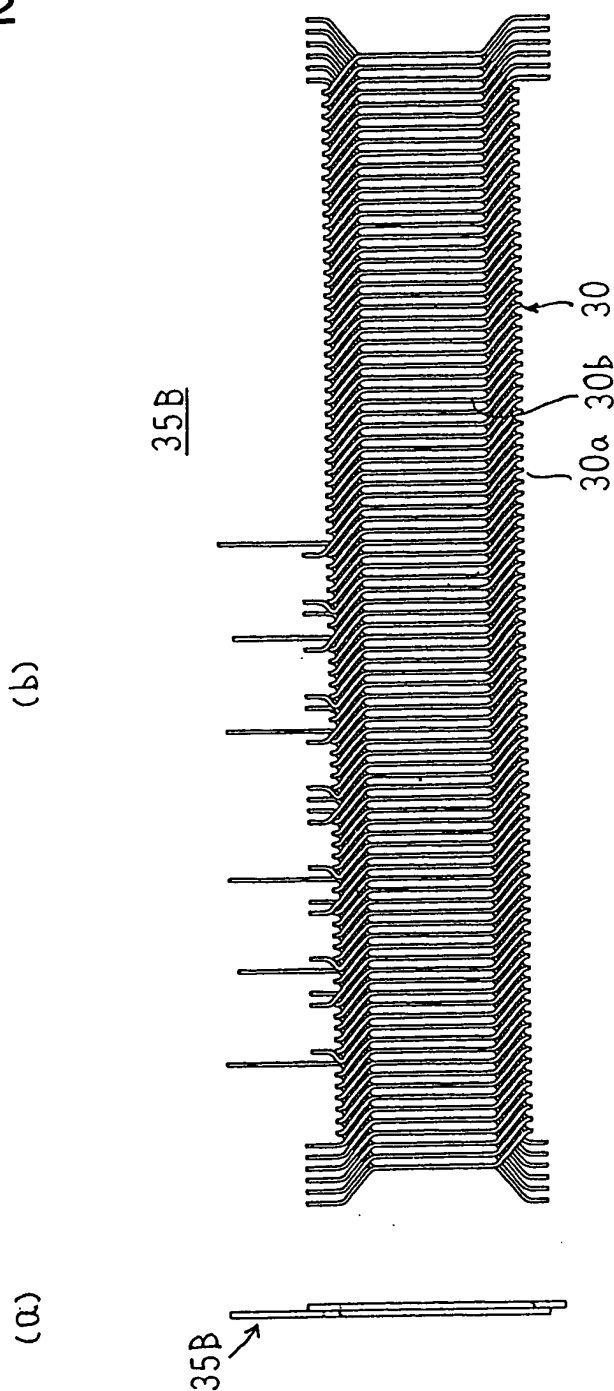


FIG. 24

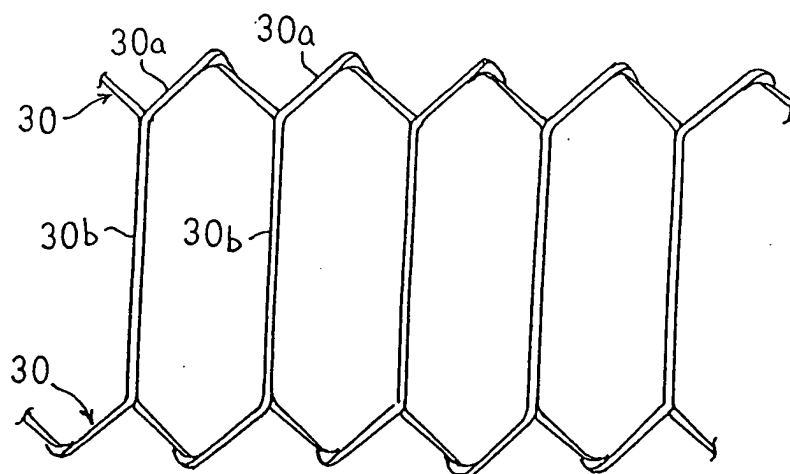


FIG. 23

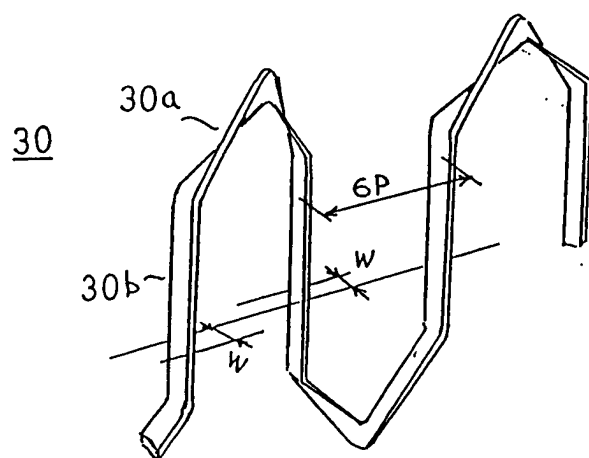




FIG. 25

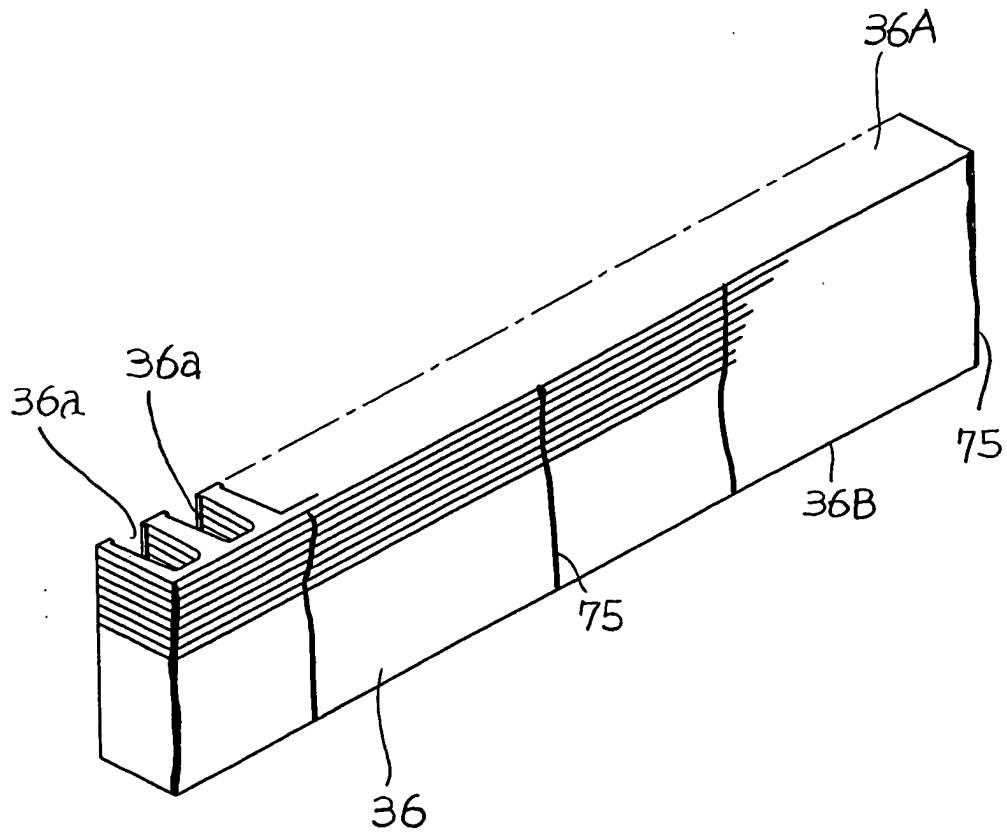
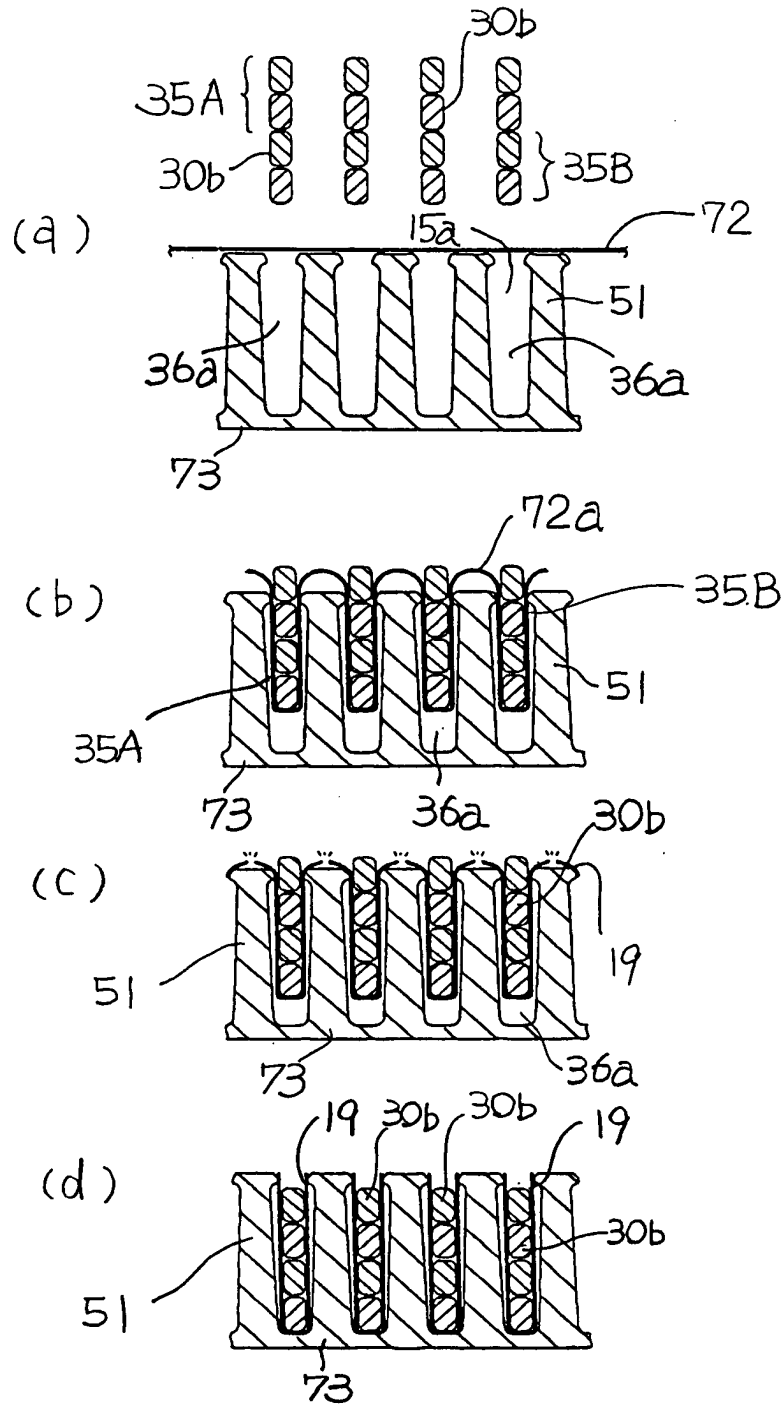


FIG. 26



This cross-sectional view shows a multi-layered printed circuit board assembly. The assembly consists of a central core (36) and two outer prepreg layers (36a). The core and prepreg layers are separated by a series of alternating conductive and insulating layers, forming a sandwich structure. The assembly is shown with a top surface and a bottom surface, with various conductive traces and vias visible on both sides. The label 35A.35B is positioned to the left of the assembly, and the labels 36 and 36a are positioned to the right of the assembly.

FIG. 28

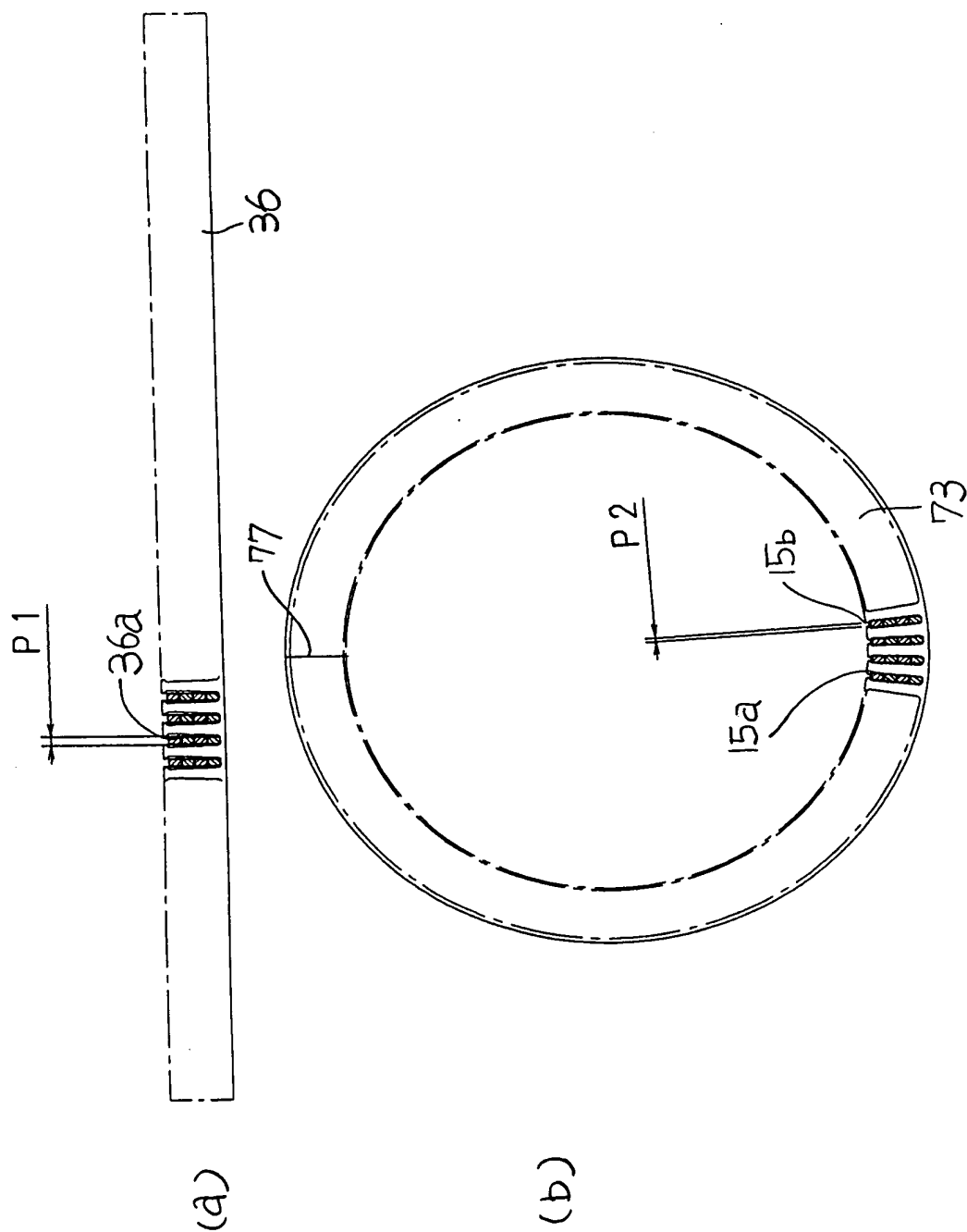


FIG. 29

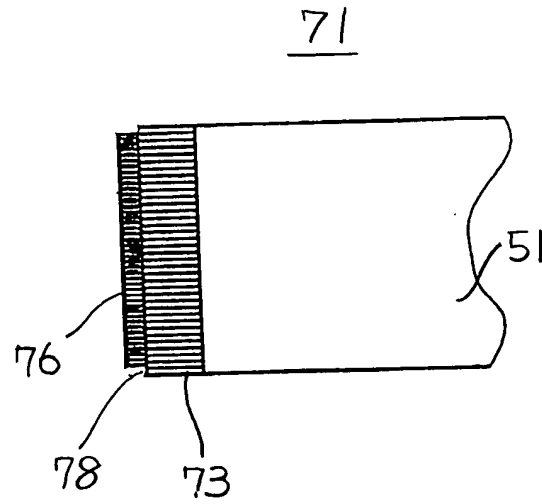


FIG. 30

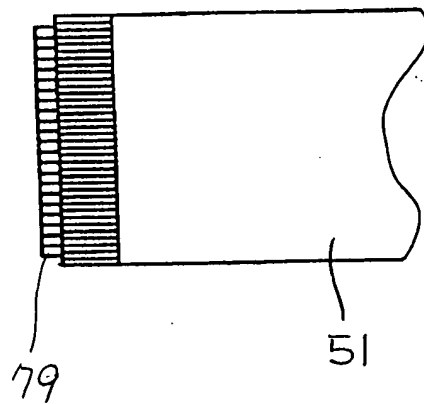


FIG. 31

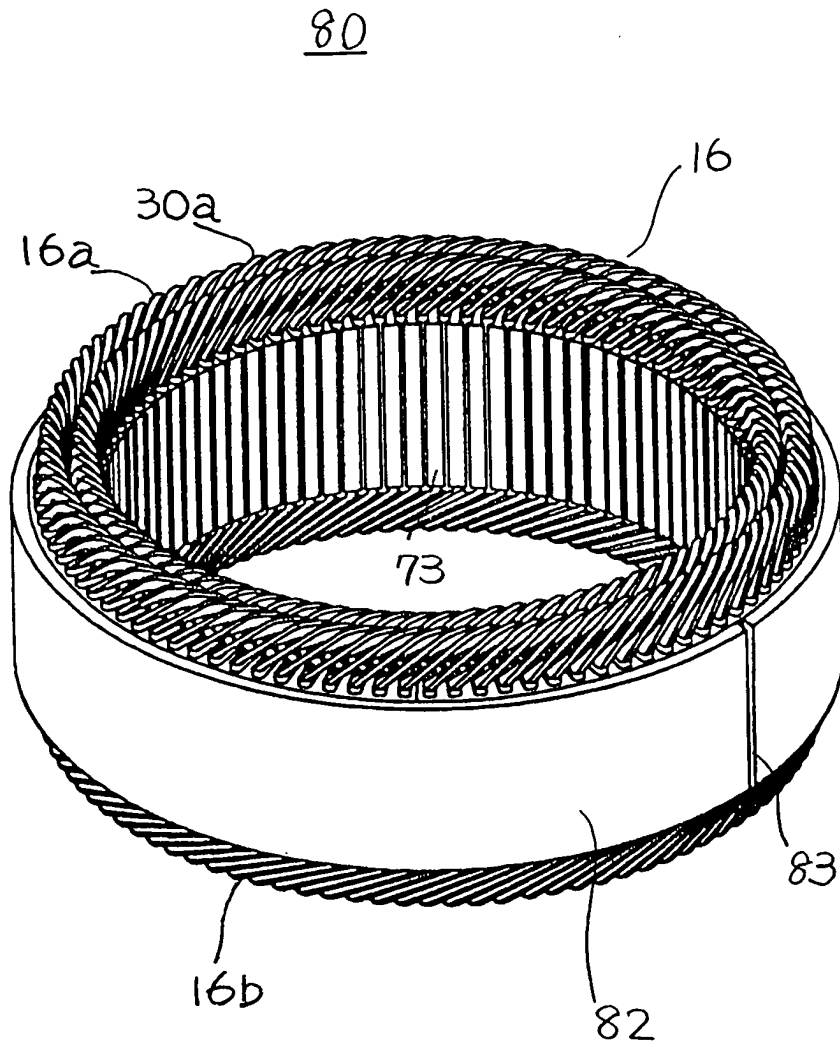


FIG. 32

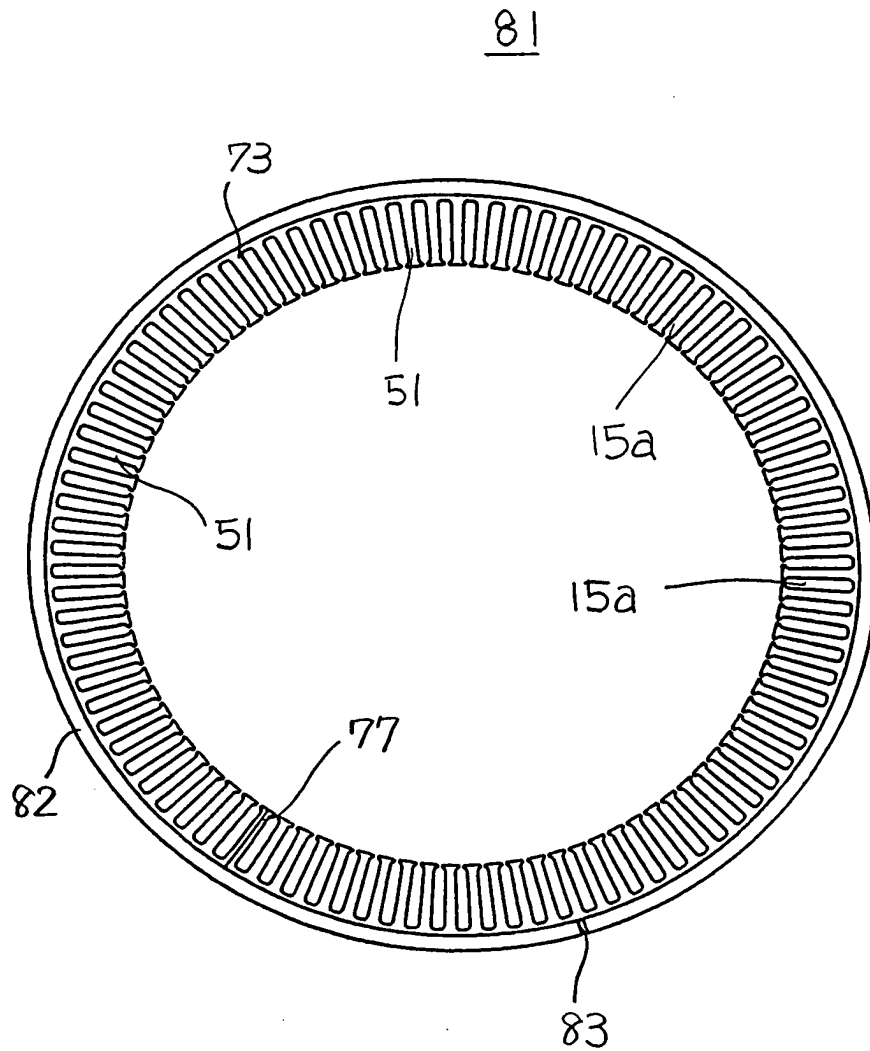


FIG. 33

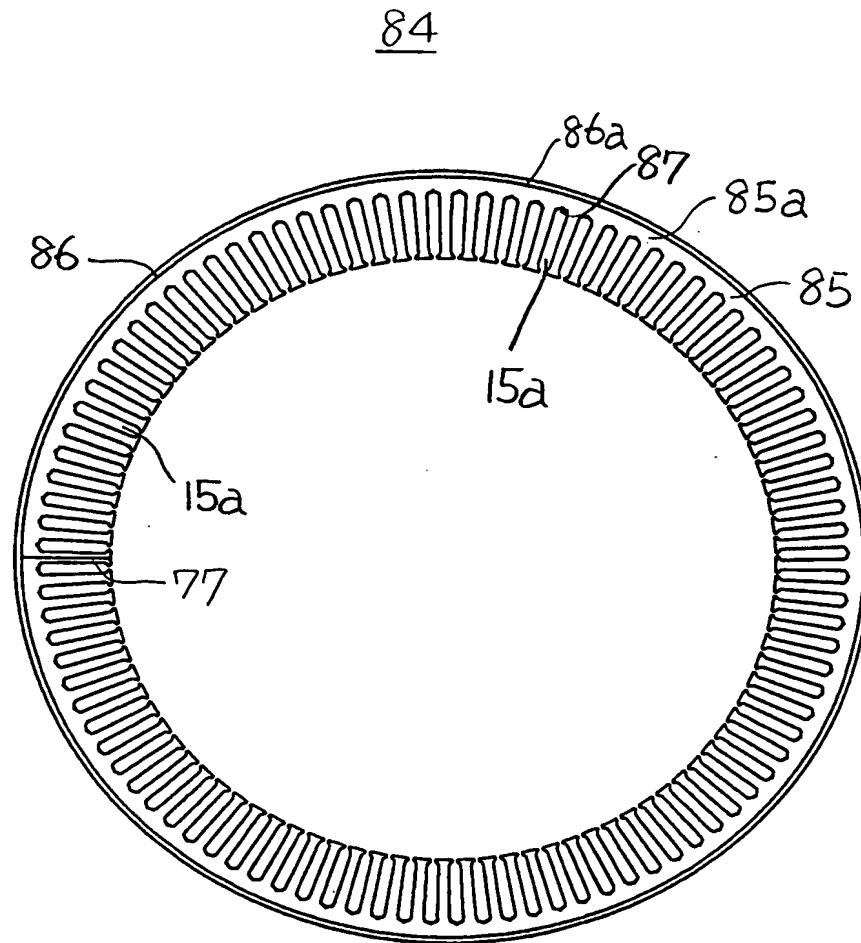


FIG. 34

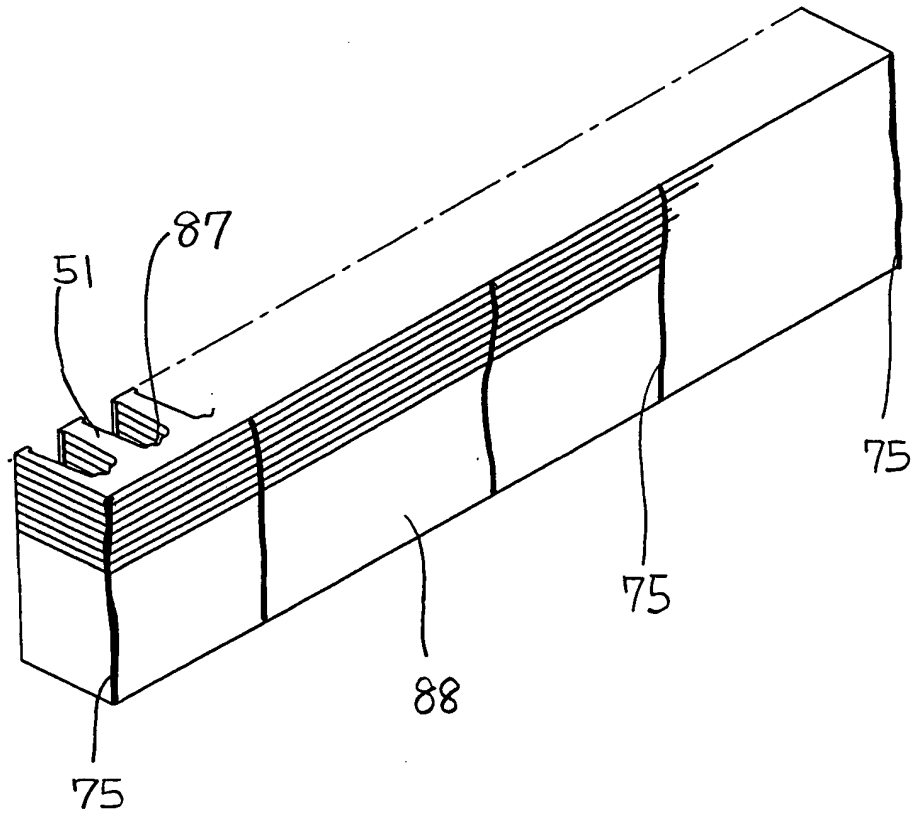


FIG. 35

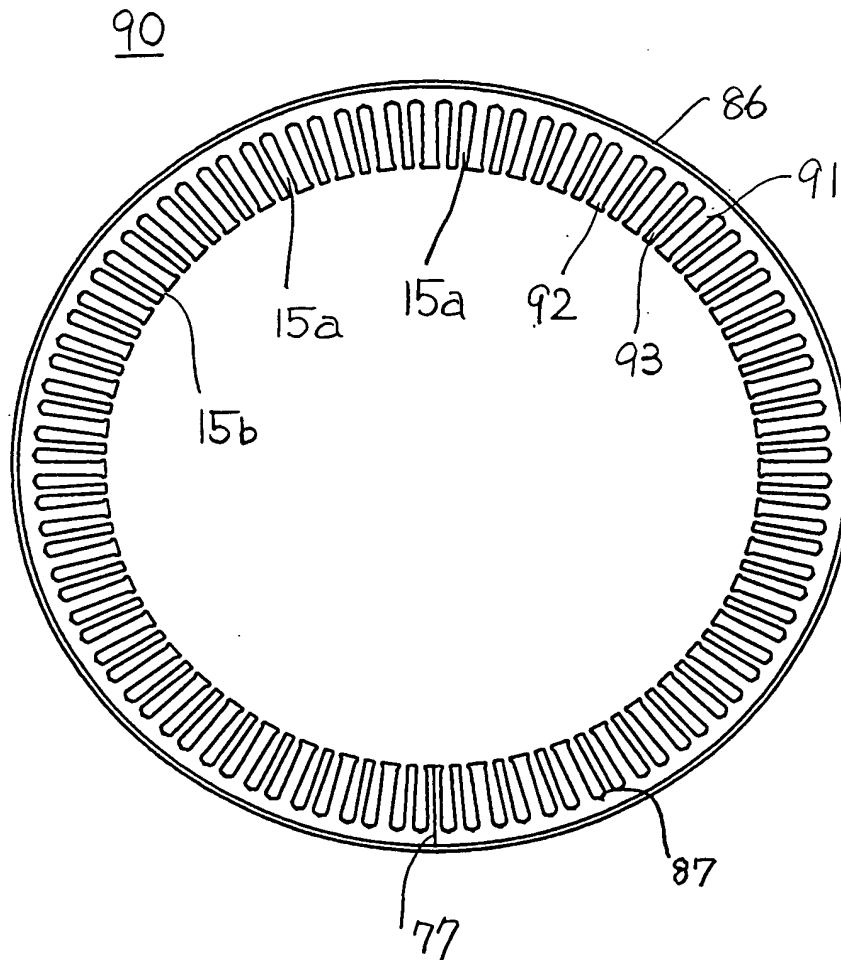


FIG. 36

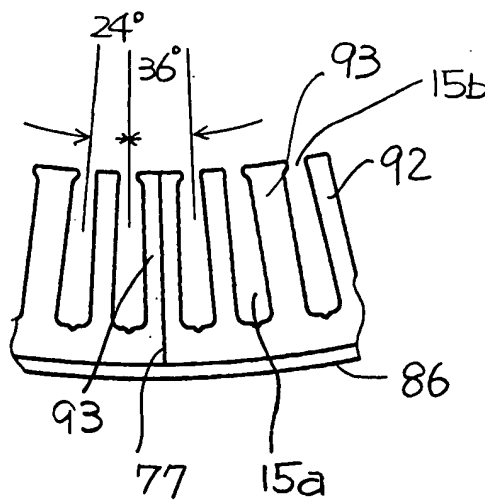


FIG. 37

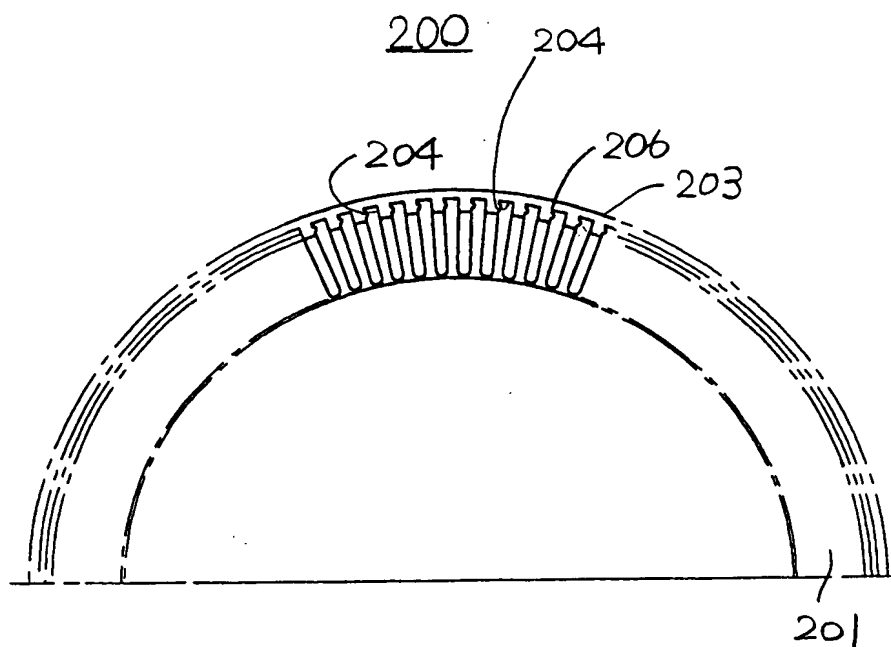


FIG. 38

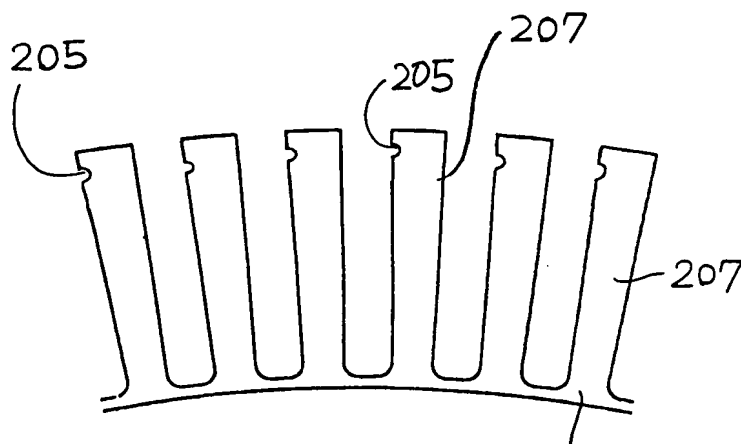


FIG. 39

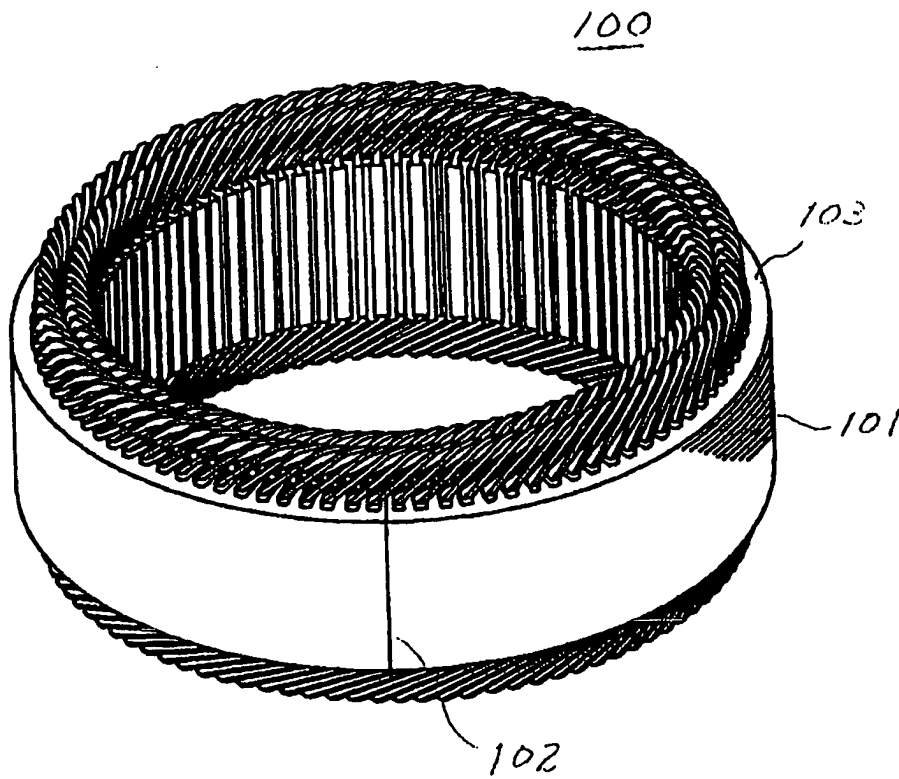


FIG. 40

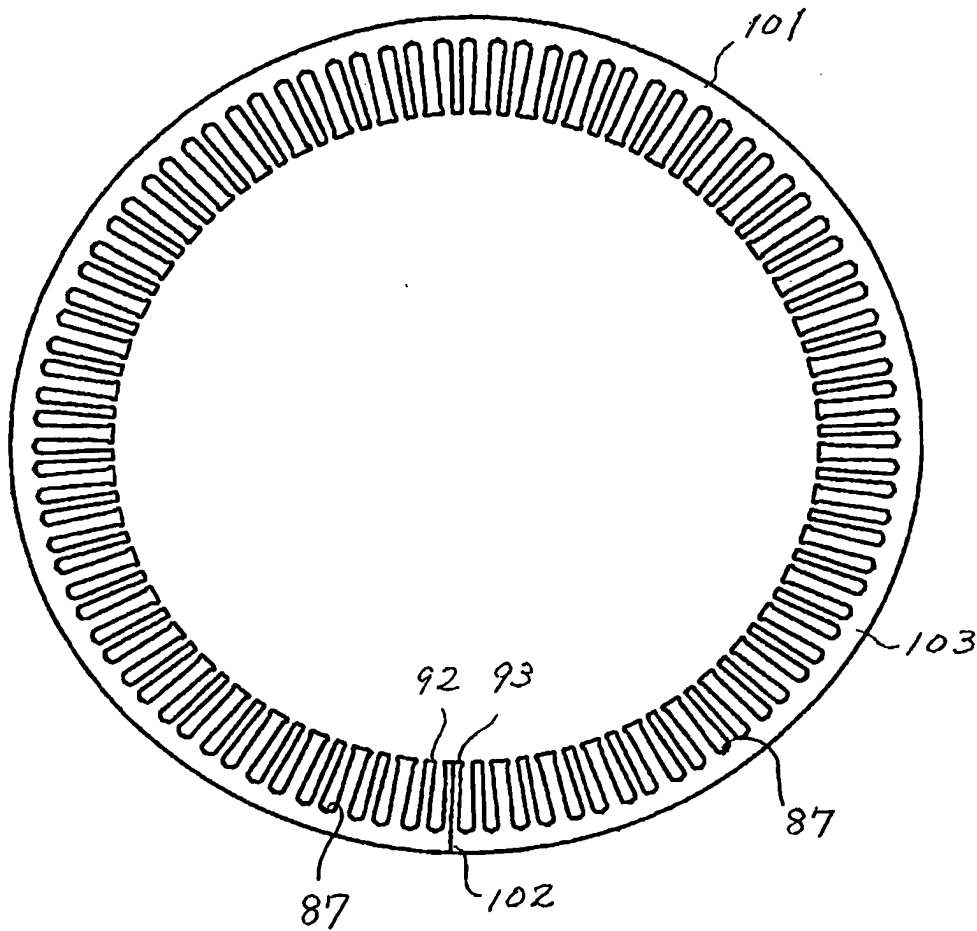




FIG. 41

PRIOR ART

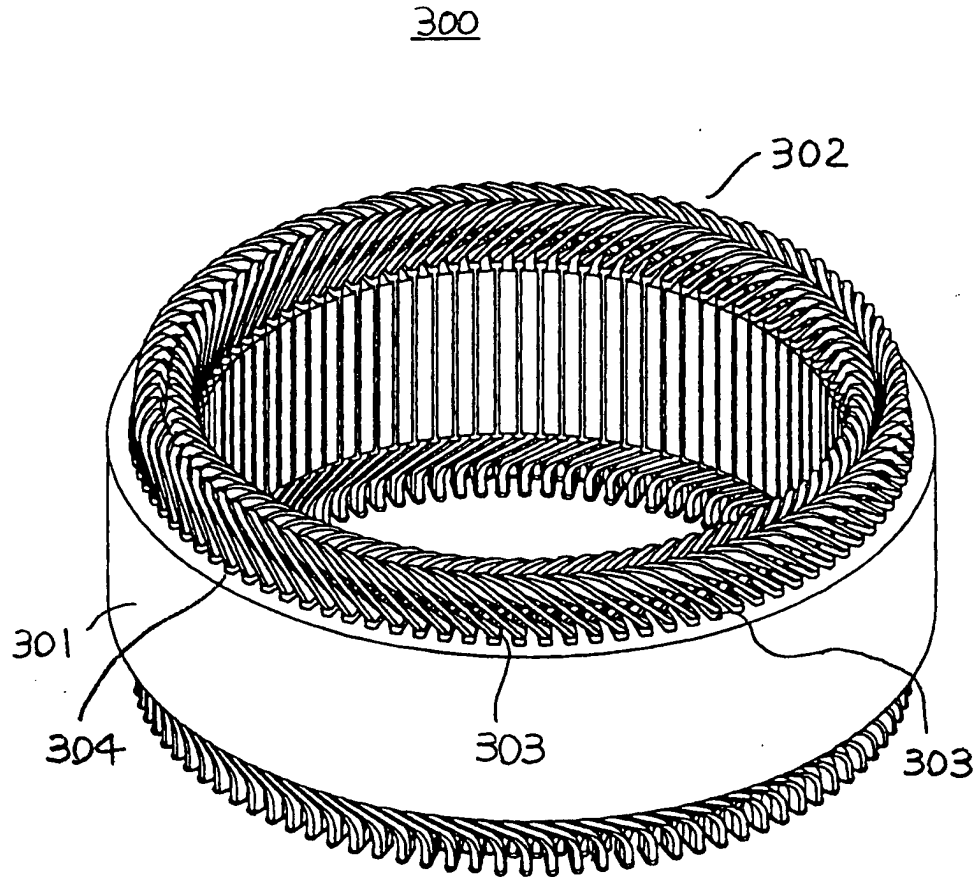




FIG. 42

PRIOR ART

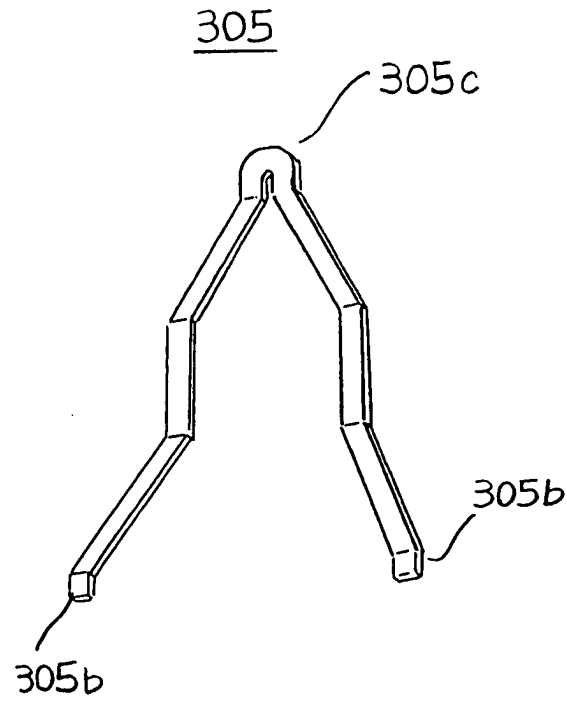


FIG. 43

PRIOR ART

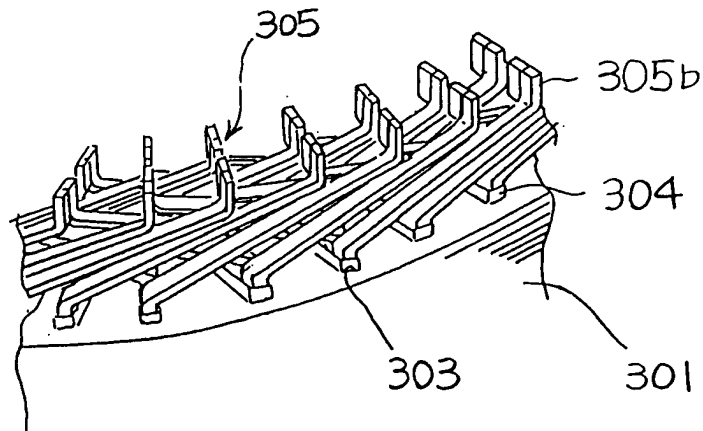
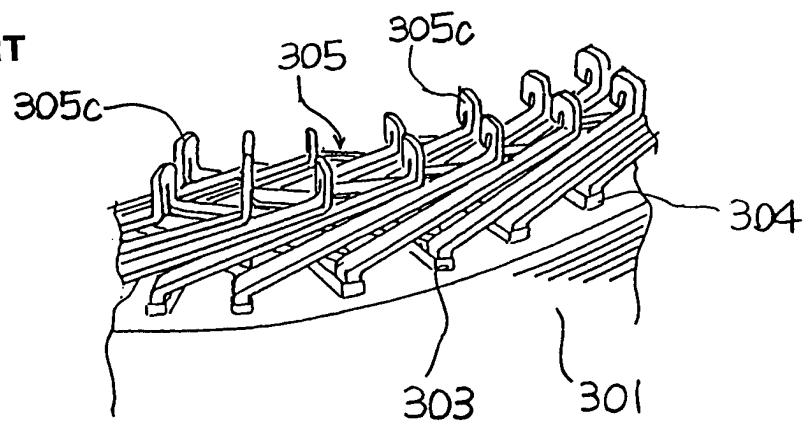


FIG. 44

PRIOR ART



SHEET 1 OF 2
ASAC ET AL
APPL. NO. 00/000000
FILED 10/00/00
ALTERNATIVE
Q. 0.000



FIG. 45

PRIOR ART

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